

67,200-327; TSMC 00-112
Serial Number 09/885,784

Gp/2823
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FEB 12 2003
TECHNOLOGY CENTER 2800

SUBSTITUTE AMENDMENT AND RESPONSE TO OFFICE ACTION

TO: COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

FROM: Tung & Associates
838 West Long Lake Road - Suite 120
Bloomfield Hills, MI 48302

DATE: 27 January 2003

REF: APPLICANT : Liang
SERIAL NO. : 09/885,784
ART UNIT : 2823
FILING DATE : 20 June 2001
ATT'Y NO. : 67,200-327; TSMC 00-132
EXAMINER : Julio J. Maldonado
TITLE : Laminating Method for Forming Integrated Circuit
Microelectronic Fabrication

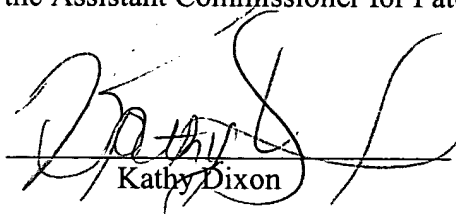
#10
Amdt #10
OSMalt/Logan
2/25/03

Not responsive
do not enter
GSI/103
Sir:

In response to an office communication mailed on 21 January 2003, please
consider the following amendments and remarks pertaining to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with sufficient postage as first
class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington,
D.C. 20231 on January 30, 2003.


Kathy Dixon